

Applic. No. 10/698,074

Amdt. dated June 29, 2005

Reply to Office action of April 5, 2005

Specification Amendments

Replace the paragraph between lines 18-23 on page 16 with the following:

--Fig. 4b shows the arrangement of figure 4a, after the protection arrangement [[100]] 110 covers the contacts 104. As can be seen, the chips 102 are arranged on the dicing substrate 106 and spaced from each other via trenches 108. Furthermore, in one embodiment, drawing of a vacuum is provided to achieve improved mold filling performance.--

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